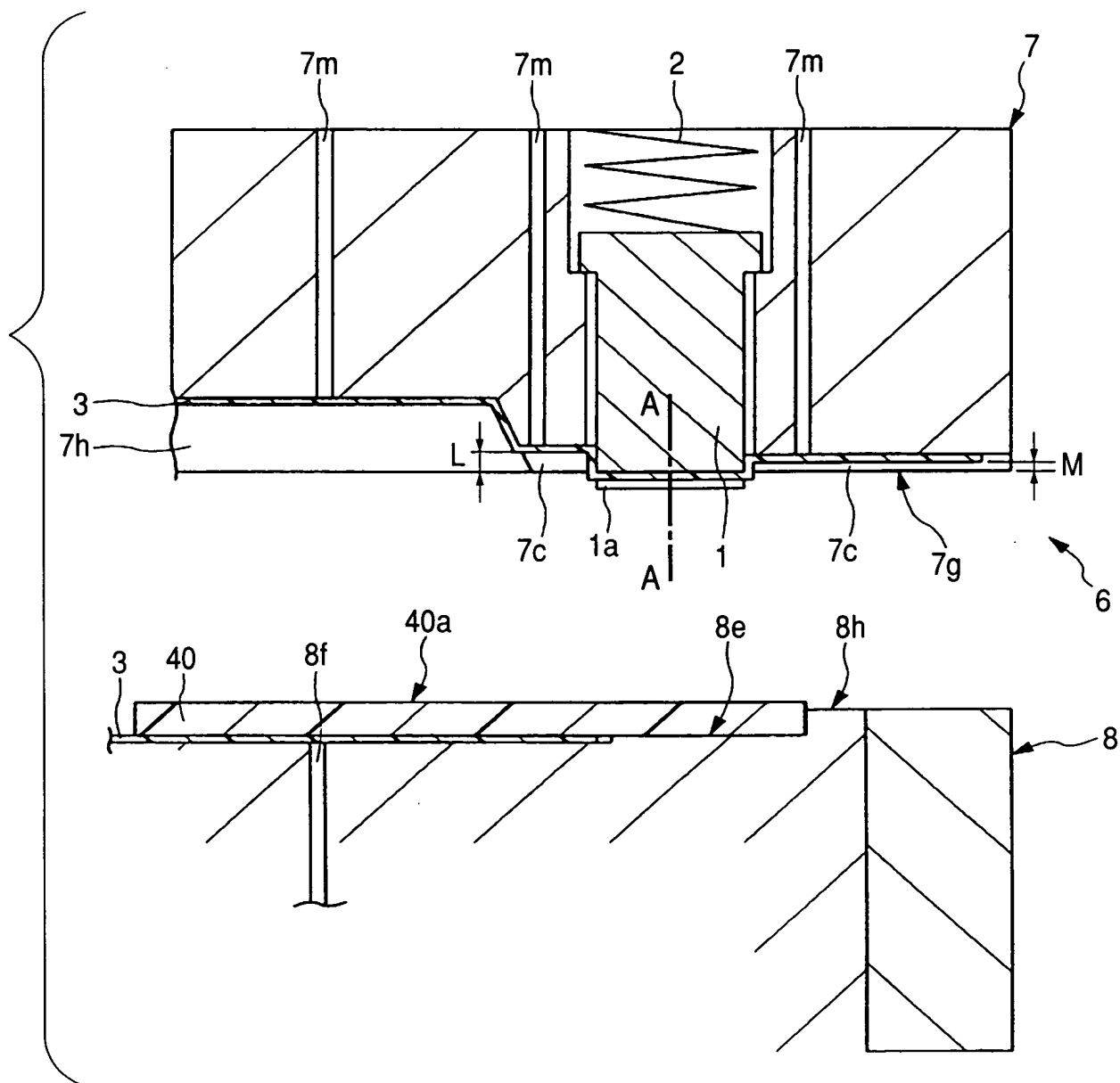
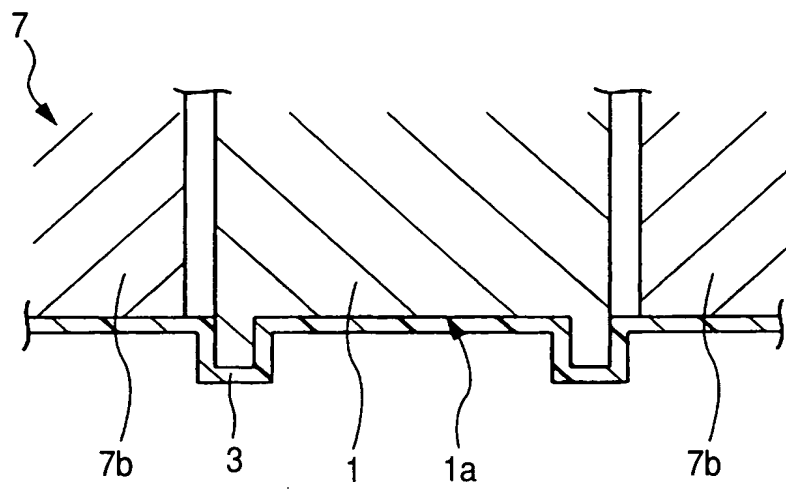


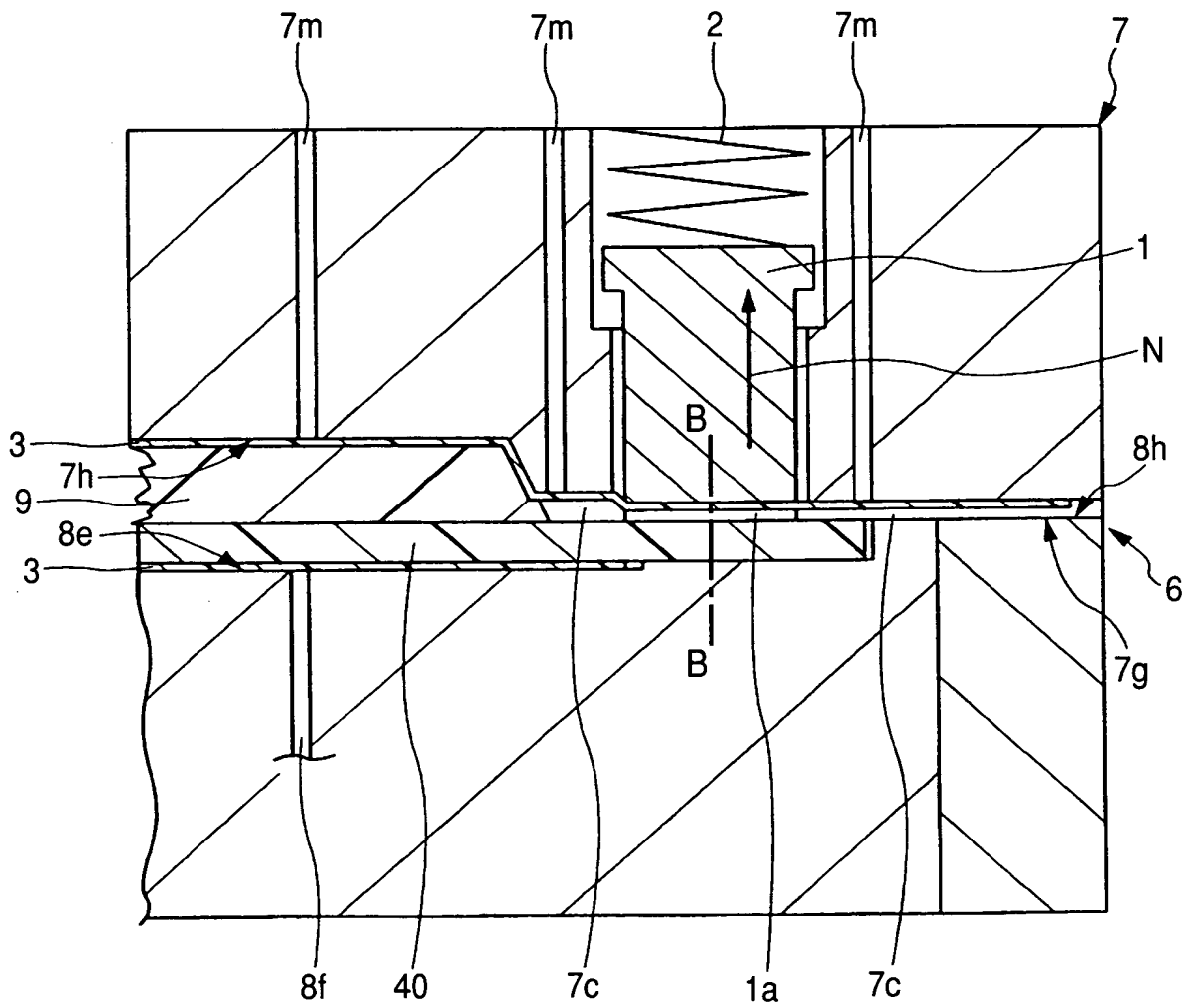
**FIG. 1**

- |                            |                                |
|----------------------------|--------------------------------|
| 1: MOVABLE PIN             | 7c: AIR VENT                   |
| 1a: GROOVE                 | 7g, 8h: MOLD SURFACE           |
| 2: SPRING FOR DRIVING      | 7h: COLLECTIVE CAVITY          |
| MOVABLE PIN (SPRING)       | 7m, 8f: SUCTION HOLE           |
| 3: FILM                    | 8: LOWER MOLD (SECOND MOLD)    |
| 6: FORMING MOLD            | 40: MULTI-CAVITY BOARD (BOARD) |
| 7: UPPER MOLD (FIRST MOLD) |                                |

**FIG. 2**

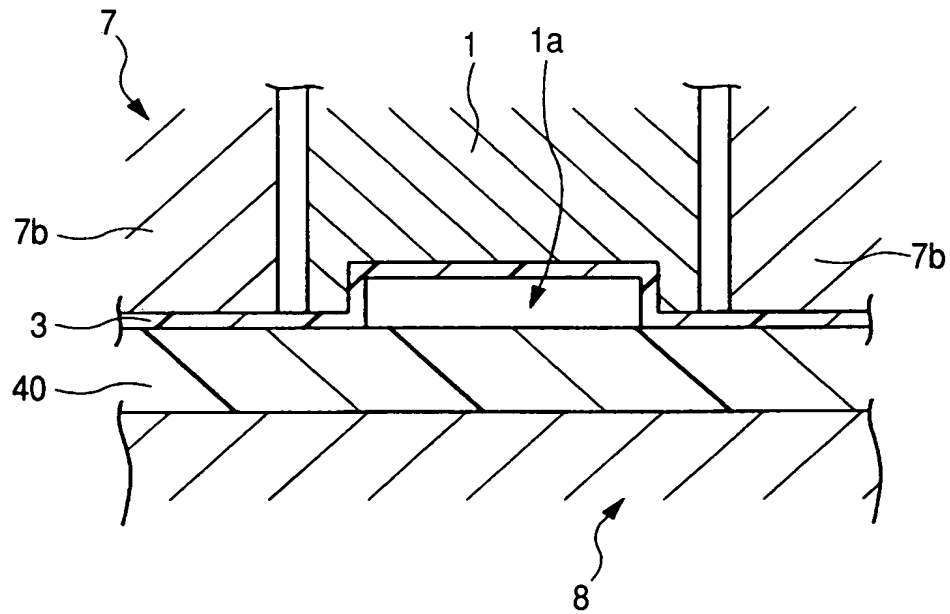


**FIG. 3**

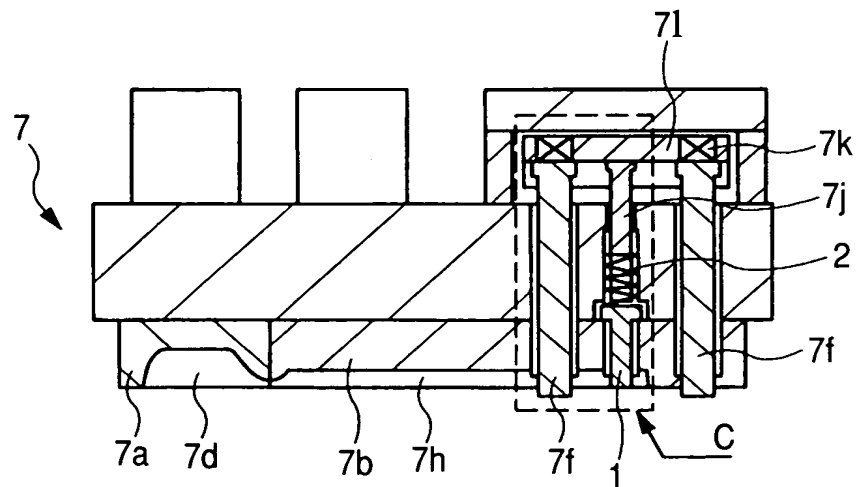


9 : SEALING RESIN

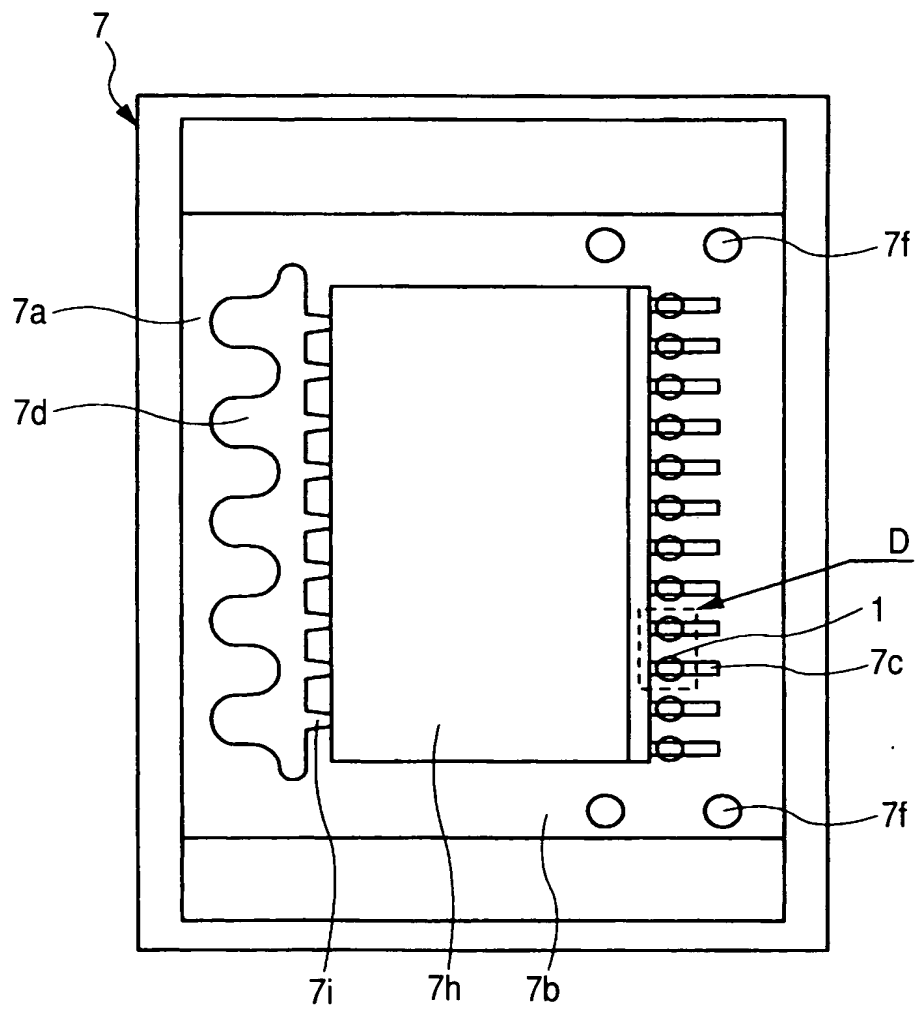
**FIG. 4**



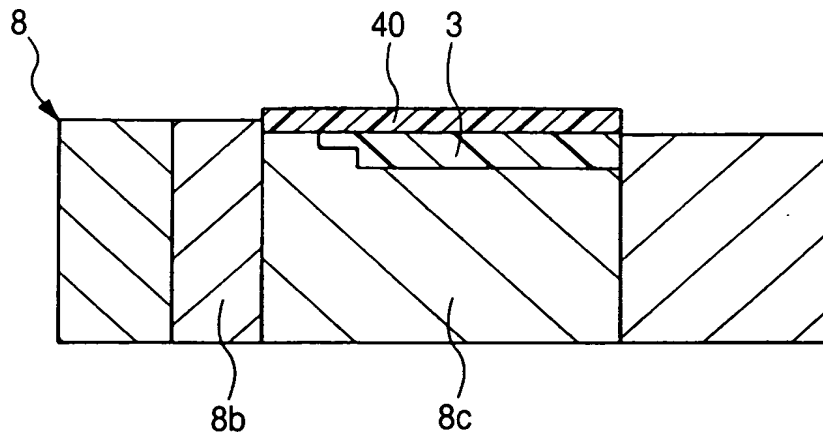
**FIG. 5**



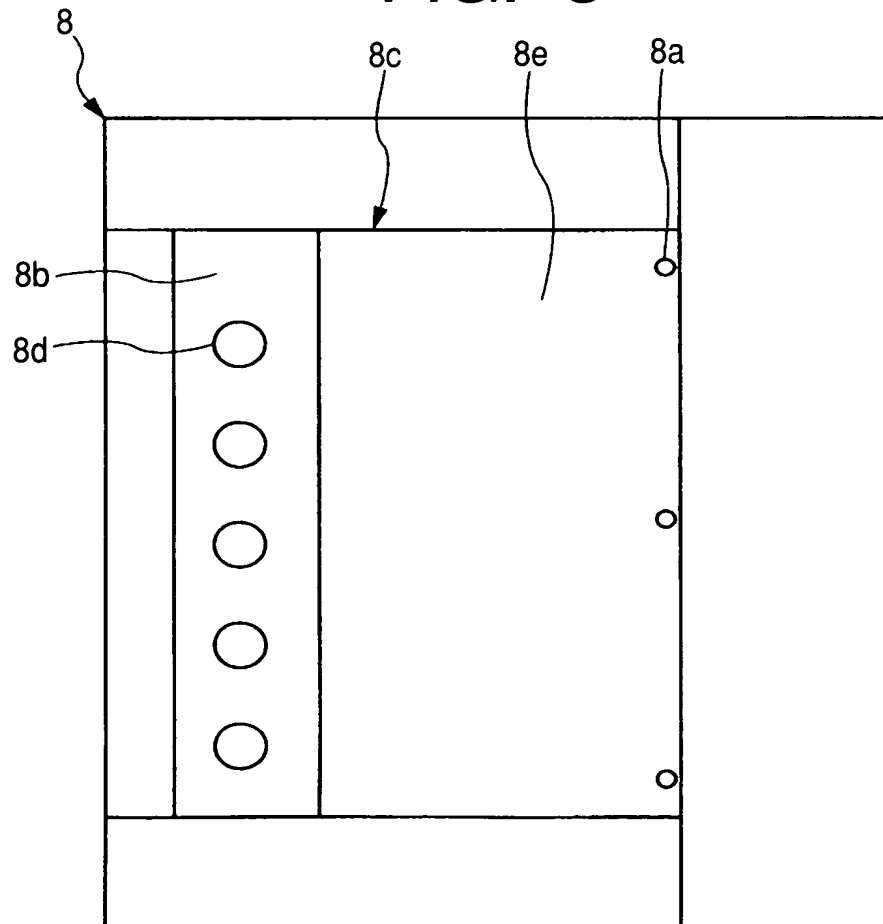
7j: RAMMER FOR MOVABLE PIN (PUSHER ROD)

**FIG. 6**

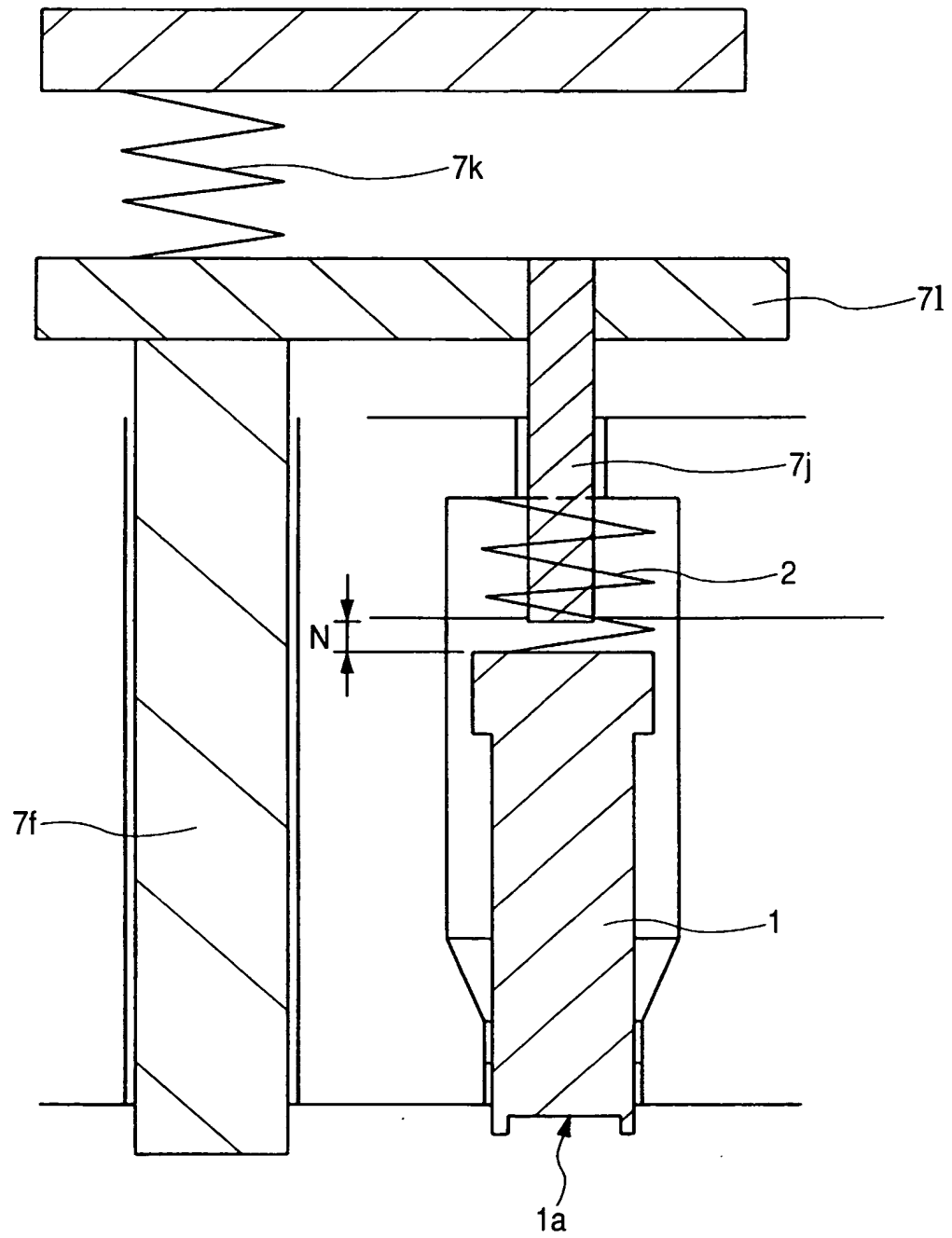
**FIG. 7**

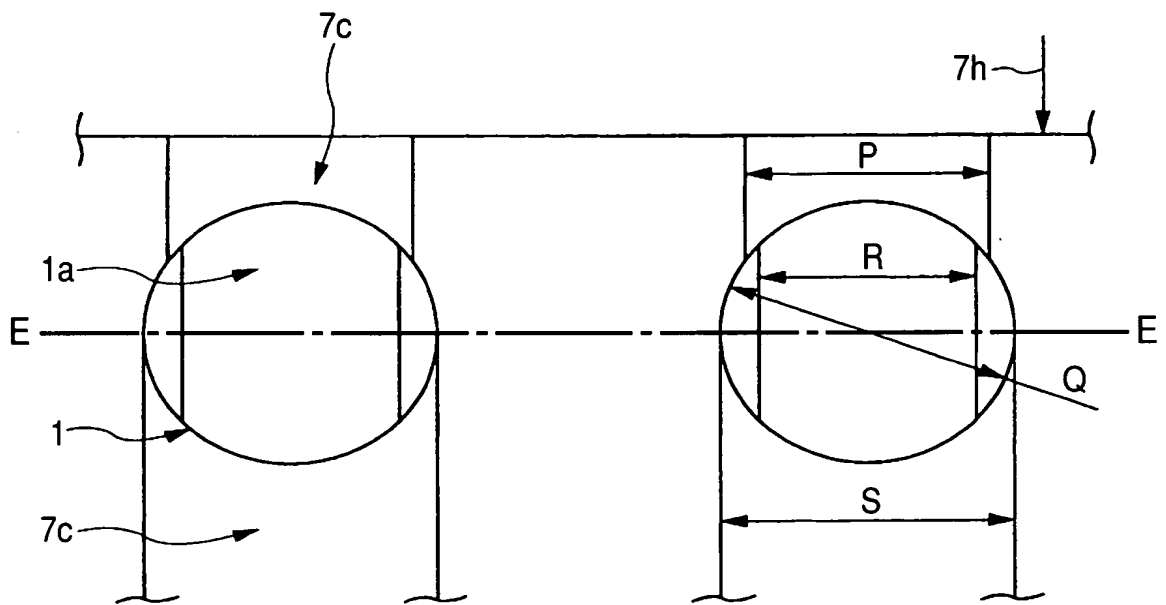


**FIG. 8**



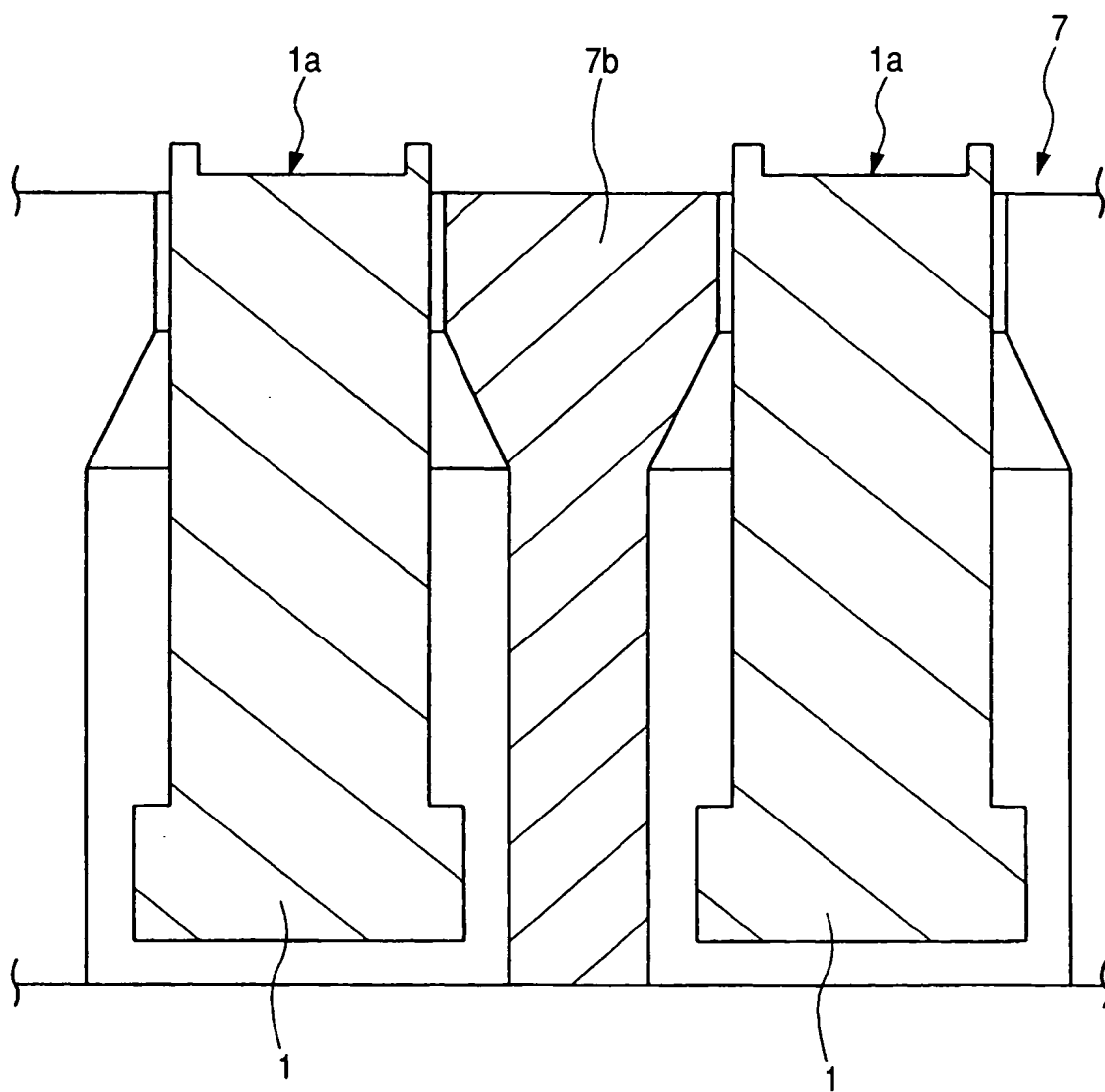
**FIG. 9**



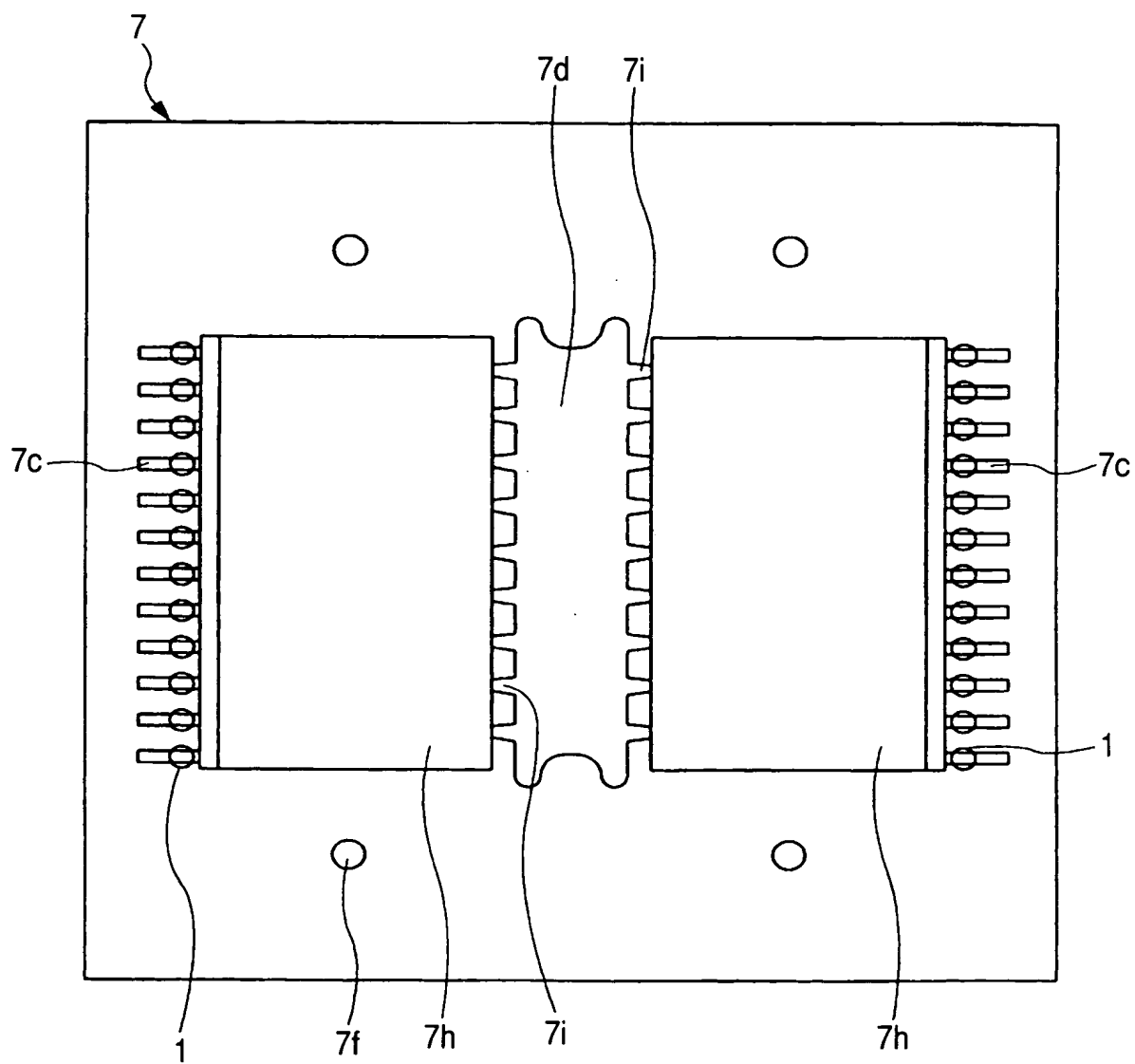
*FIG. 10*



**FIG. 11**



**FIG. 12**



**FIG. 13**

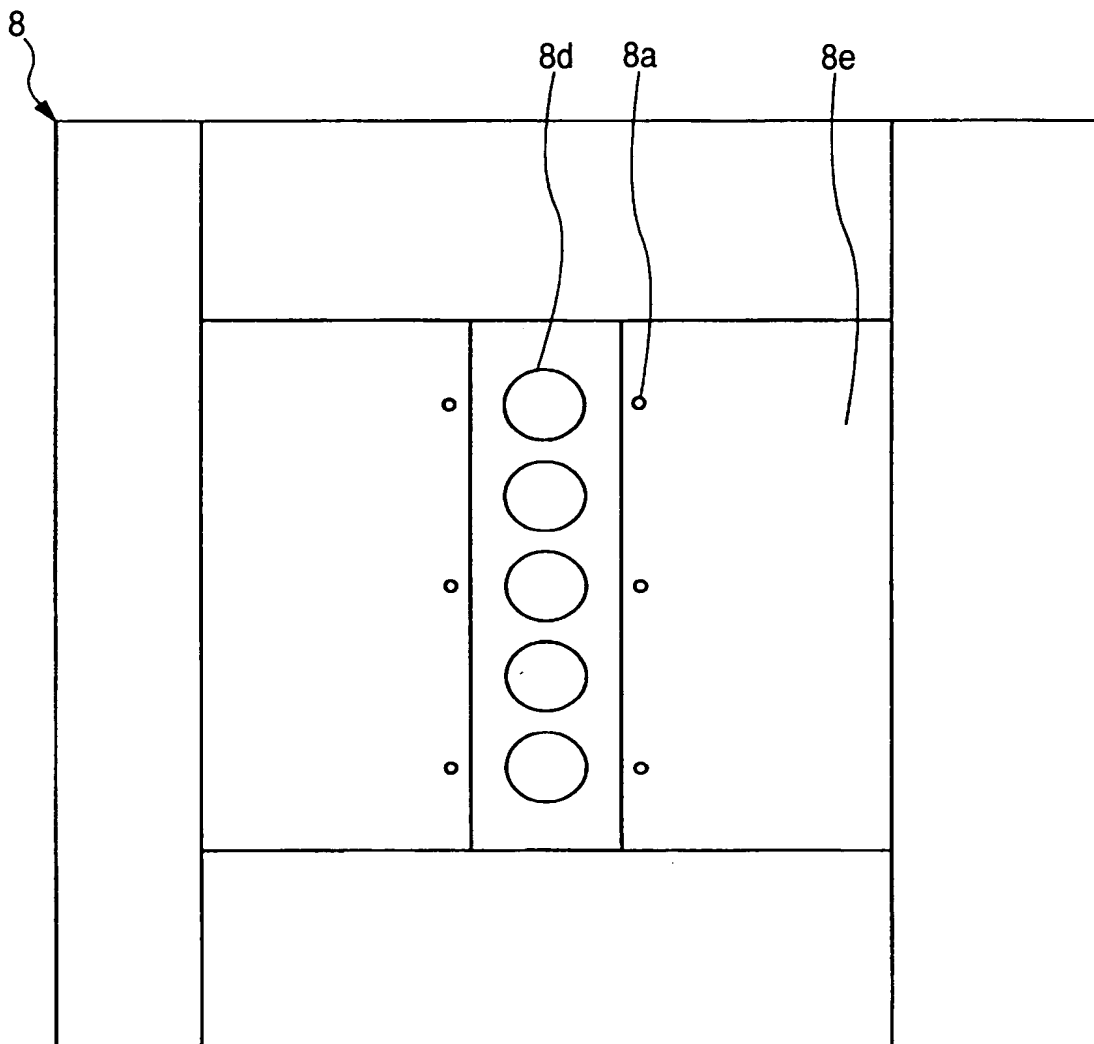
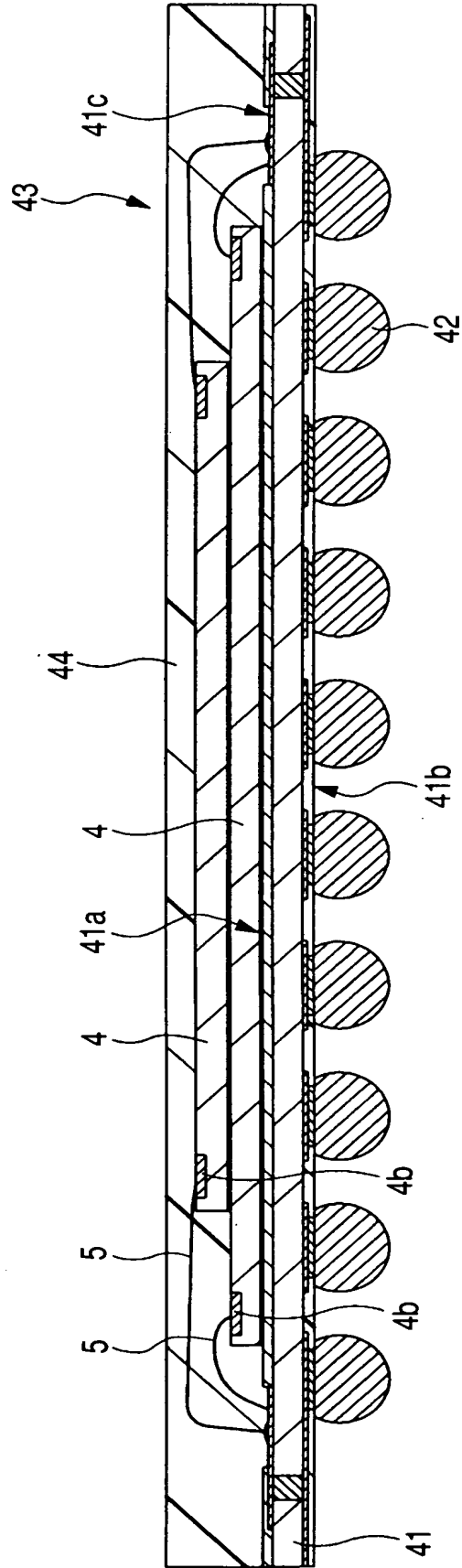
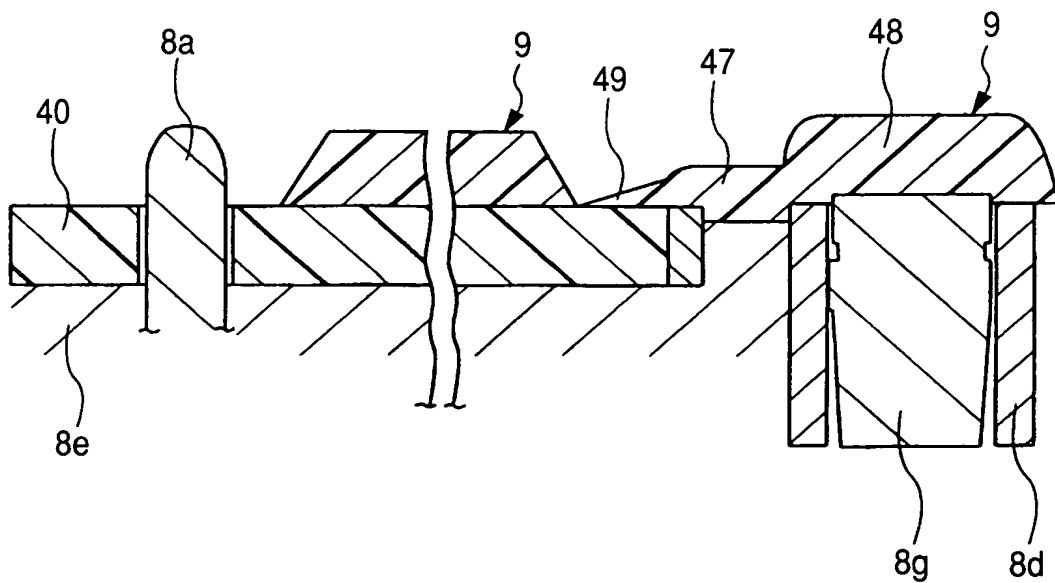


FIG. 14

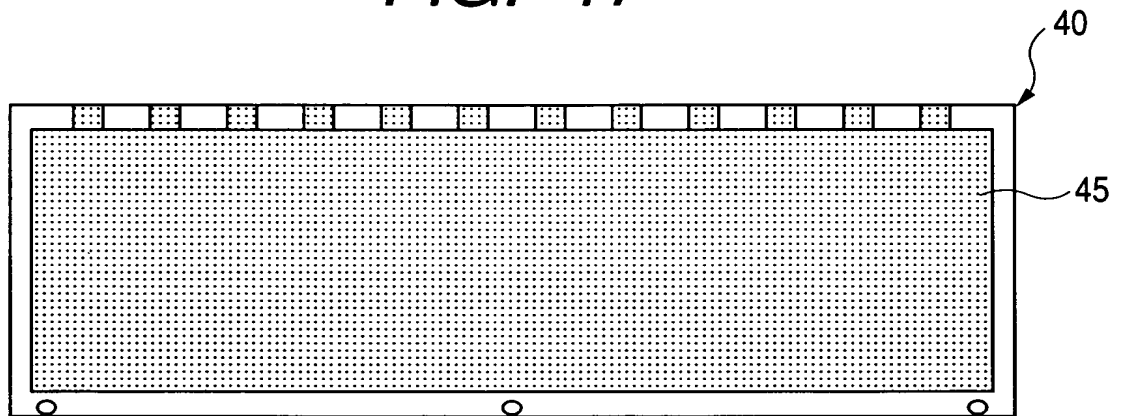


- 4 : SEMICONDUCTOR CHIP
- 41 : PRINTED WIRING BOARD (BOARD)
- 43 : CSP (SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE)

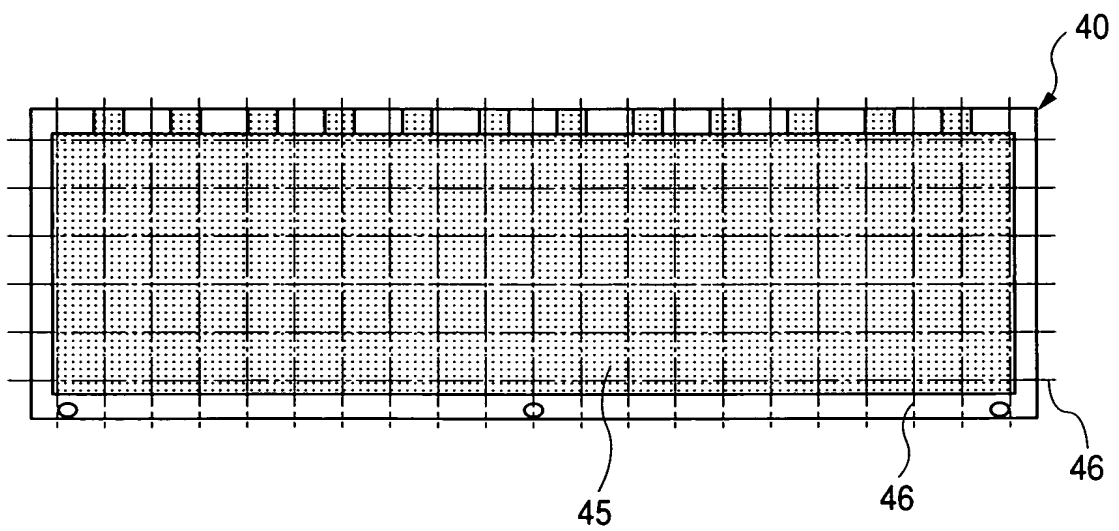
FIG. 16



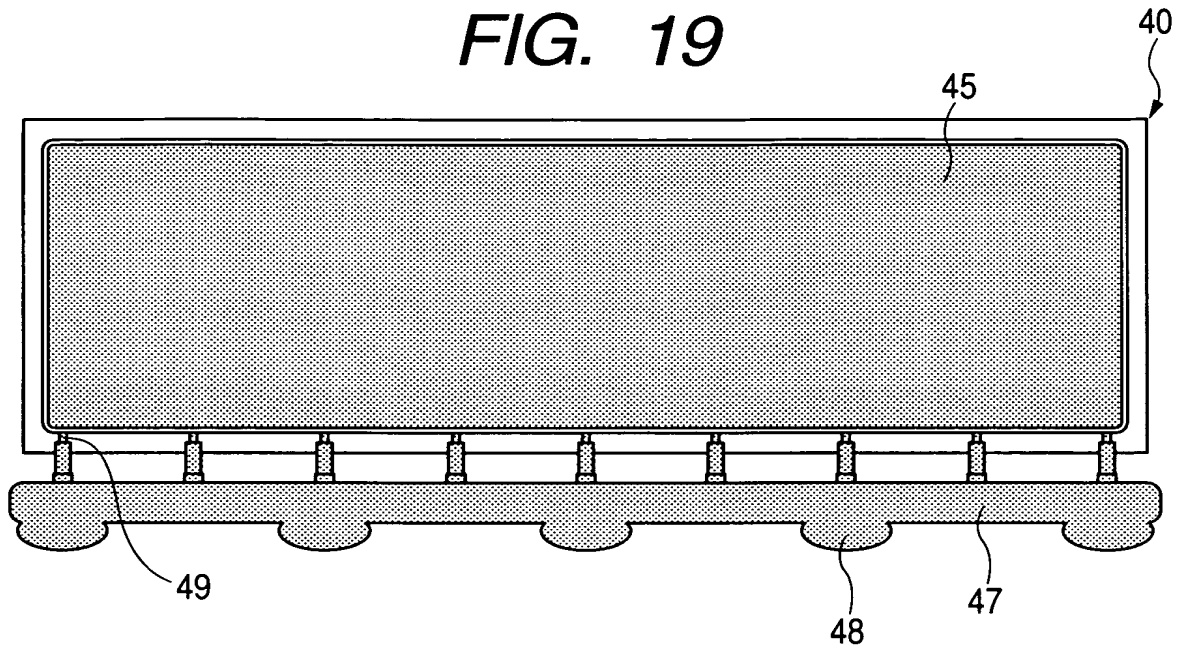
*FIG. 17*



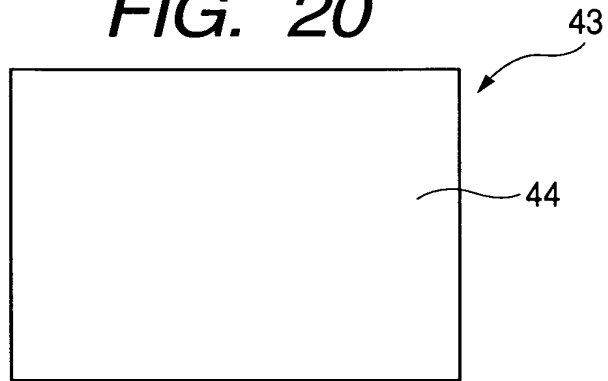
*FIG. 18*



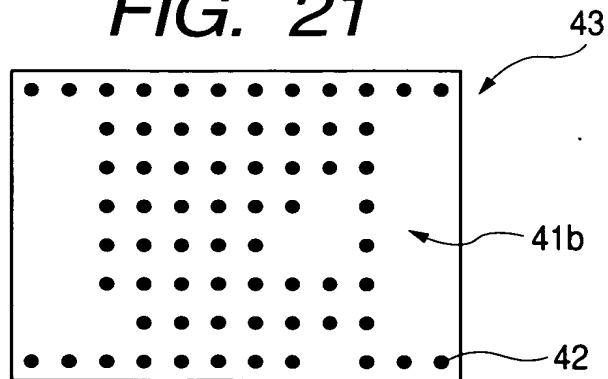
**FIG. 19**



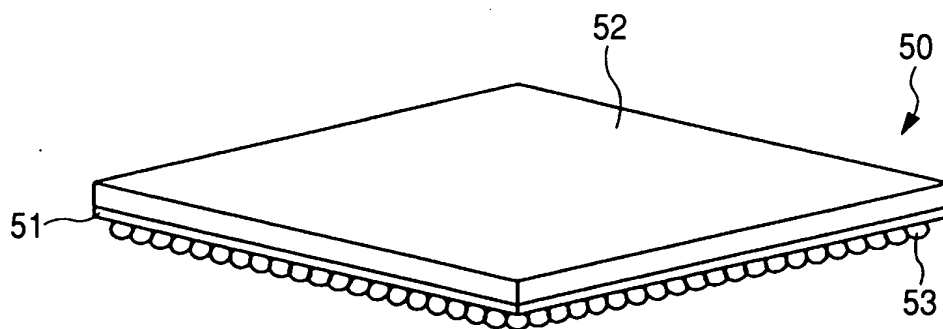
**FIG. 20**



**FIG. 21**

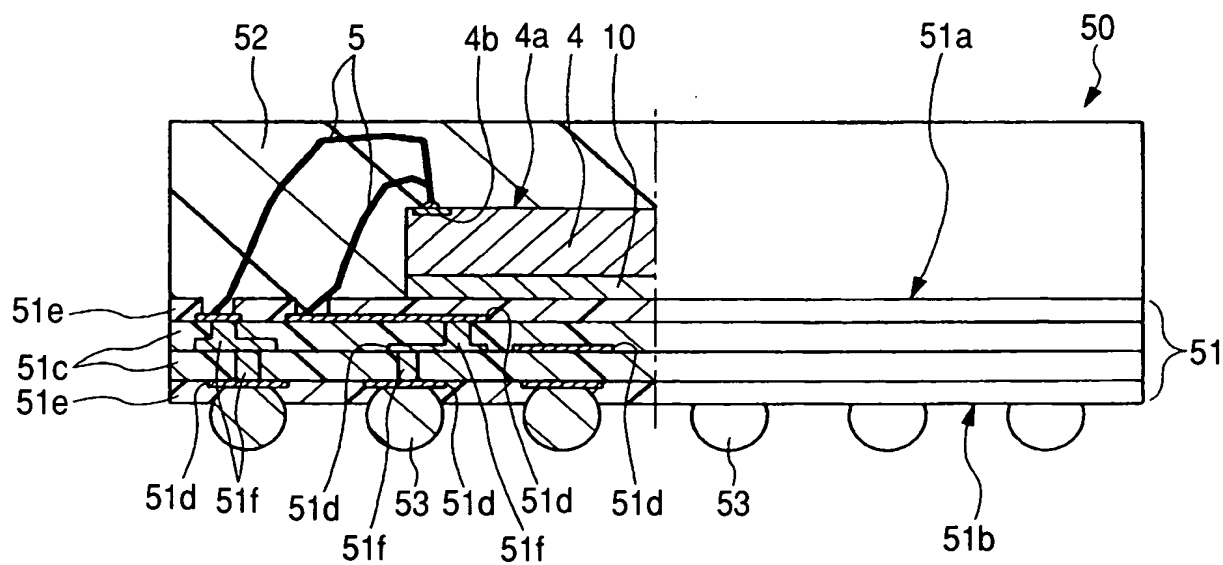


**FIG. 22**



50 : CSP (SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE)  
51 : MULTI-LAYERED PRINTED WIRING BOARD (BOARD)

**FIG. 23**



**51c : CORE MEMBER**



FIG. 24

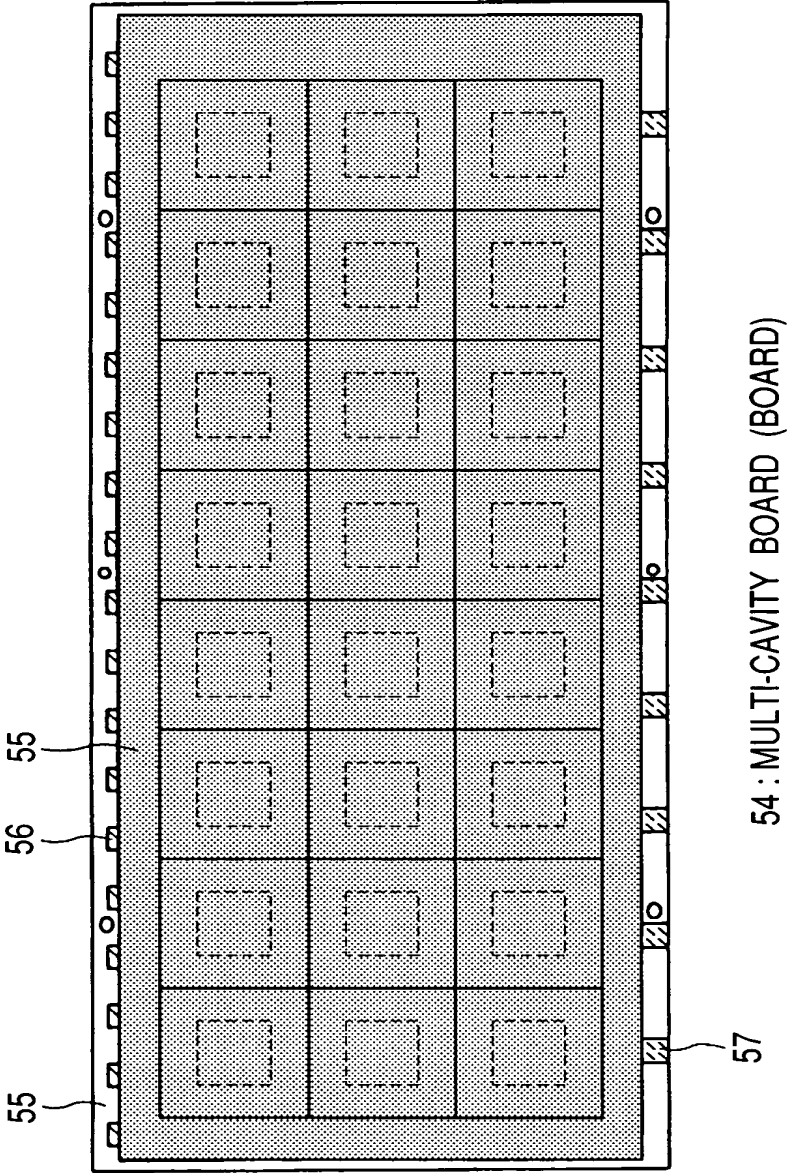


FIG. 25

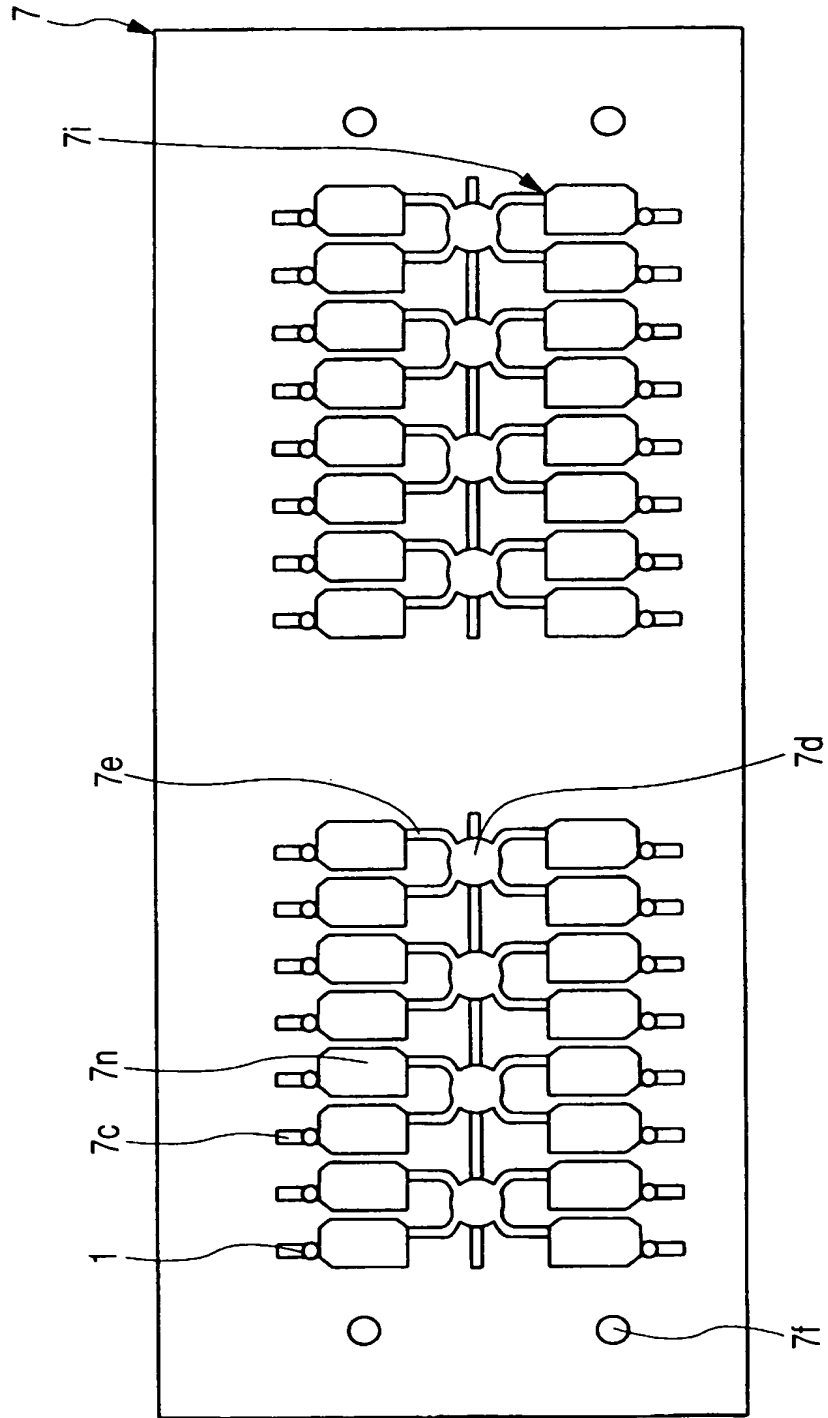


FIG. 26

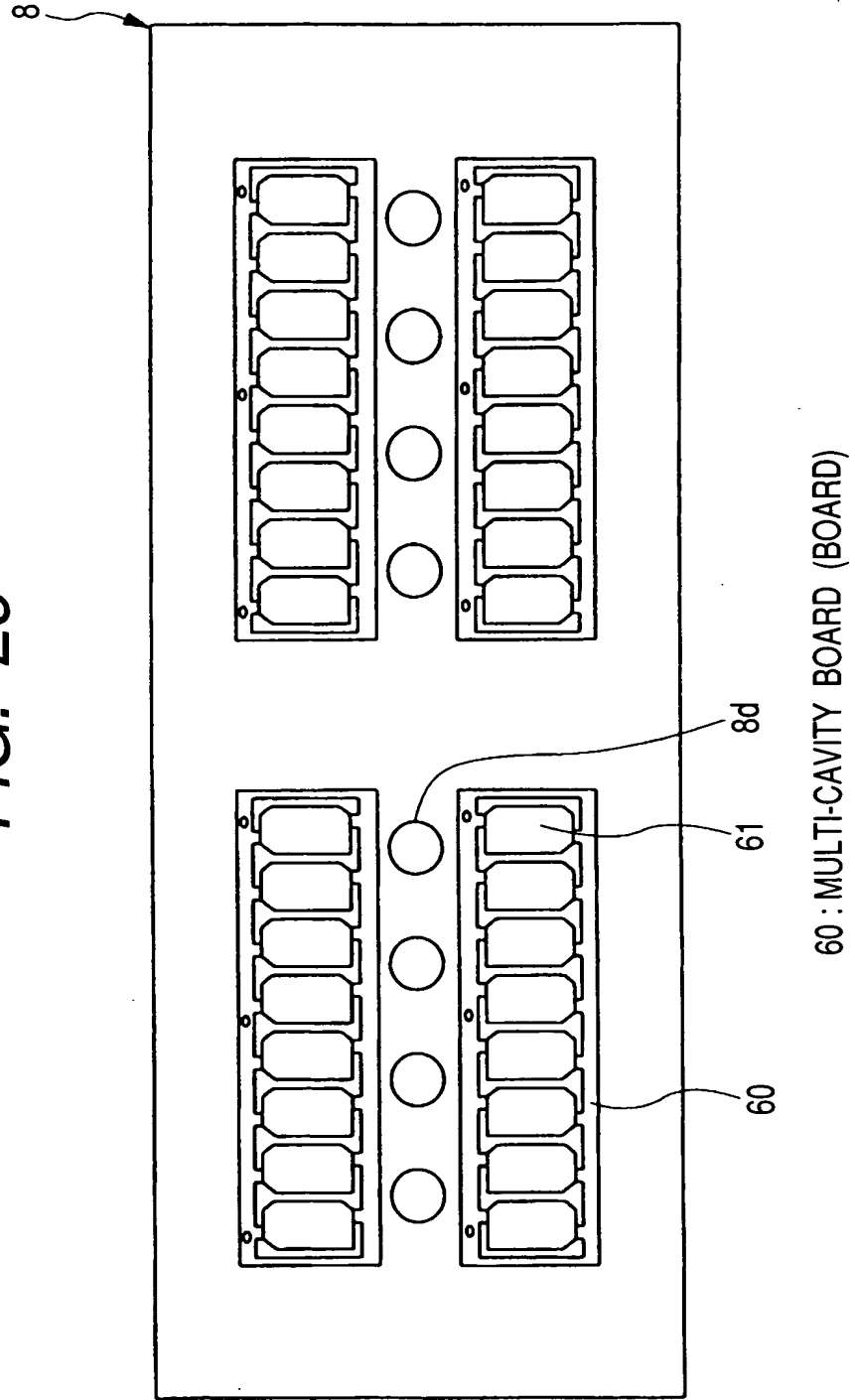
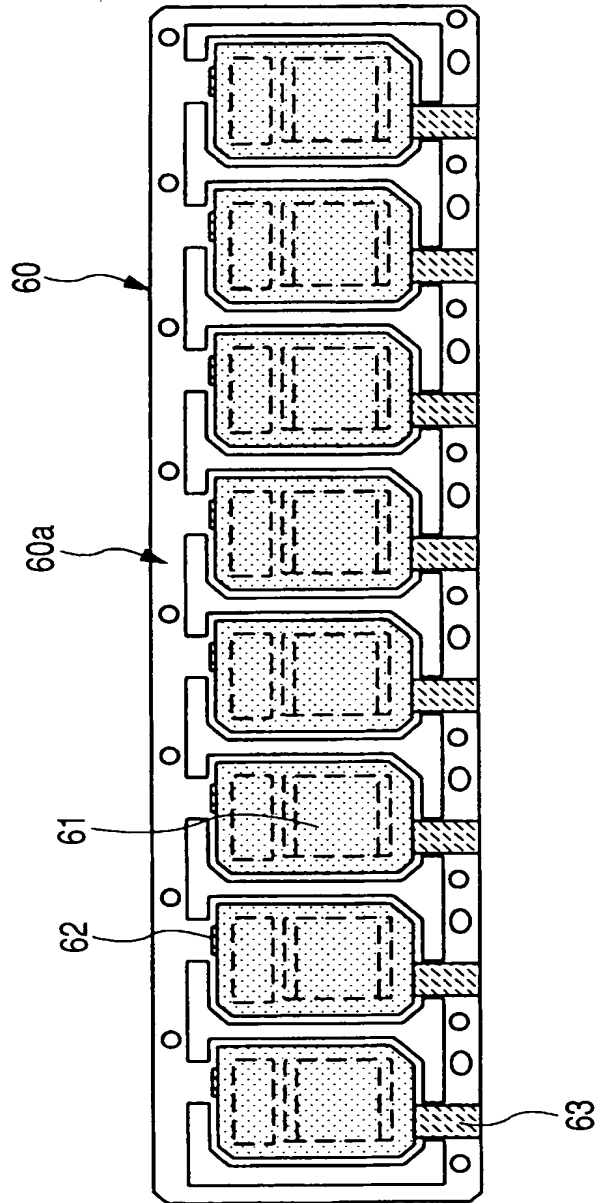
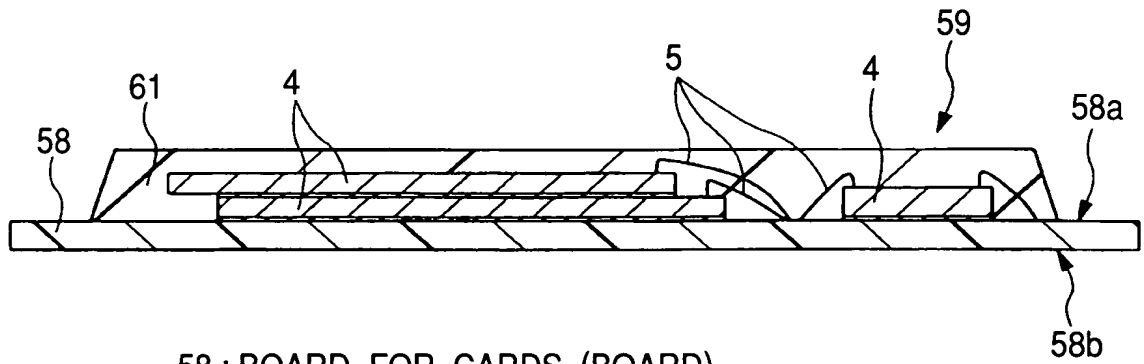


FIG. 27



**FIG. 28**

58 : BOARD FOR CARDS (BOARD)  
59 : CARD-TYPE PACKAGE  
(SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE)

**FIG. 29**